

Datasheet revision 1.1

www.chipquik.com

Thermally Stable Solder Paste NC (No-Clean) Sn96.5/Ag3.0/Cu0.5 T3 (500g jar)

Product Highlights Revolutionary Formula: No Refrigeration Required! Printing speeds up to 100mm/sec Long stencil life Wide process window Clear residue

Low voiding Excellent wetting compatibility on most board finishes Print grade Compatible with enclosed print heads RoHS 3 and REACH compliant

TS991SNL500T3

Specifications Alloy: Mesh Size: Micron (µm) Range: Flux Type: Flux Classification: Metal Load: Melting Point: Packaging:	Sn96.5/Ag3.0/Cu0.5 T3 25-45 Synthetic No-Clean REL0 88.5% Metal by Weight 217°C (423°F) 500g.Jar	
Packaging: Shelf Life:	500g Jar Refrigerated >12 months, Unrefrigerated >12 months	*See notes below:

<u>*Shelf Life Notes:</u> Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation Print Speed: 25-100mm/sec Squeegee Pressure: 70-250g/cm of blade Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life >8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

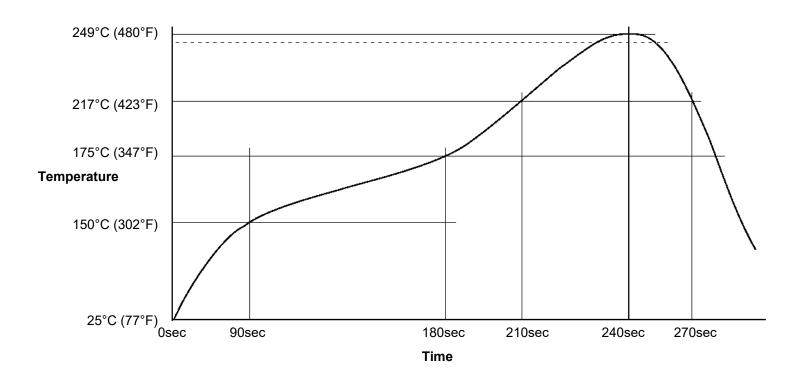
Stencil Cleaning Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store at 3-25°C (37-77°F). Do not freeze. Refrigeration is not required, but will extend shelf life. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Tack Value	IPC-TM-650: 2.4.44	64g
Viscosity – Malcom @ 10 RPM/25°C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	Print: 155-215, Dispense: 125-170
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:	
J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	
RoHS 3 Directive (EU) 2015/863:	Yes